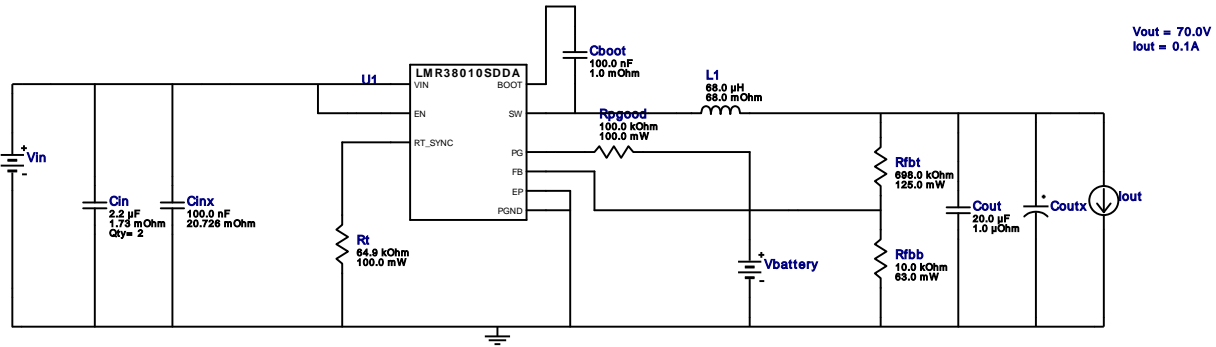


WEBENCH® Design Report

Design : 121 LMR38010SDDAR
LMR38010SDDAR 75V-75V to 70.00V @ 0.1A












Design Alerts

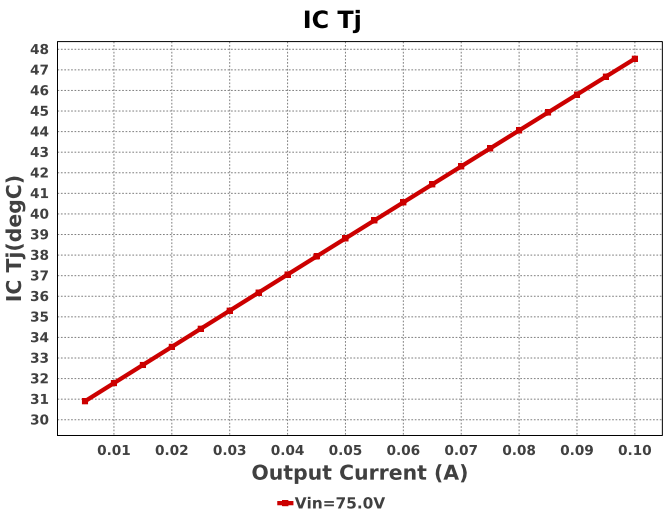
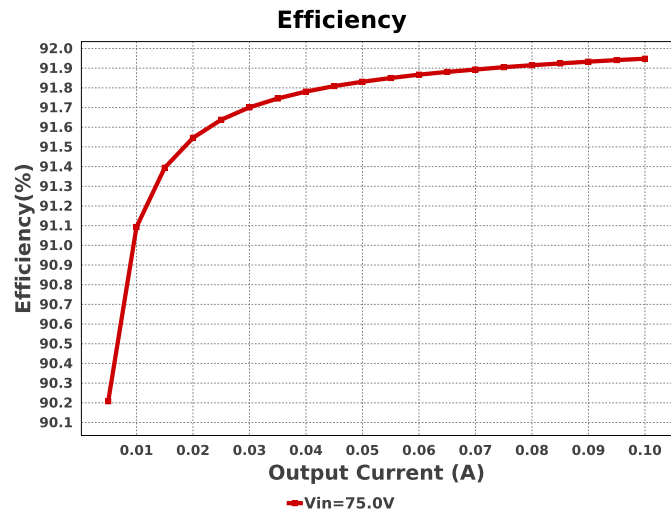
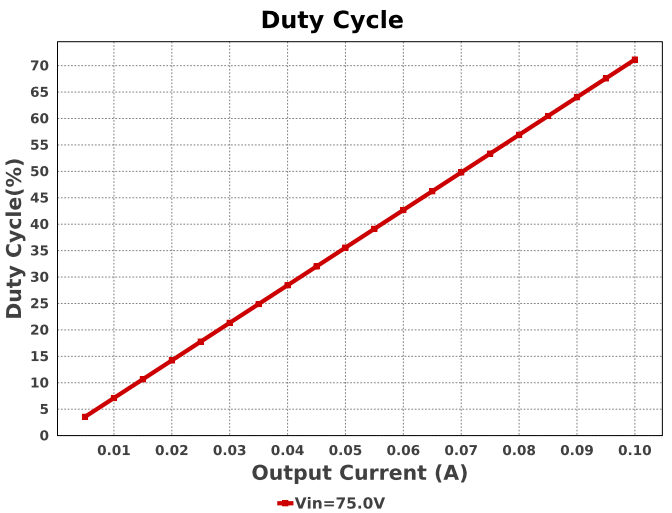
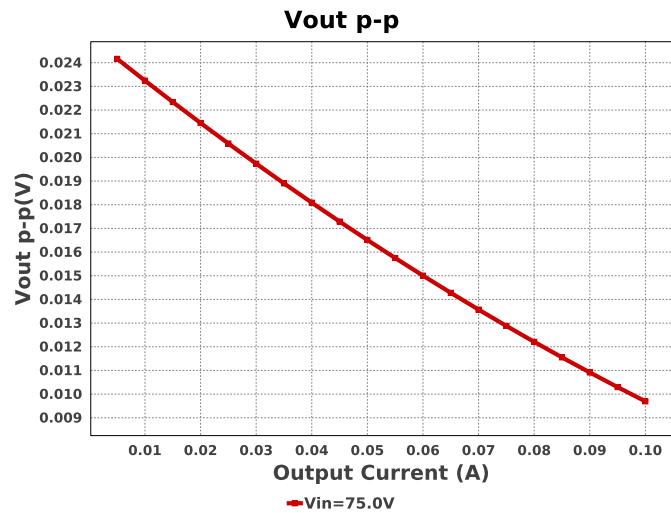
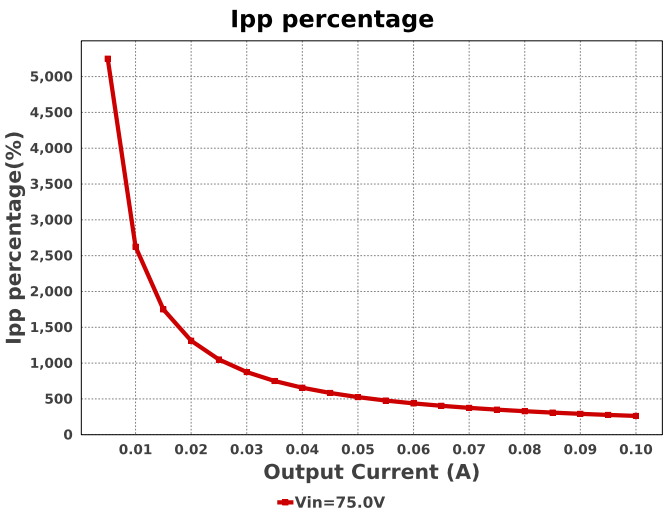
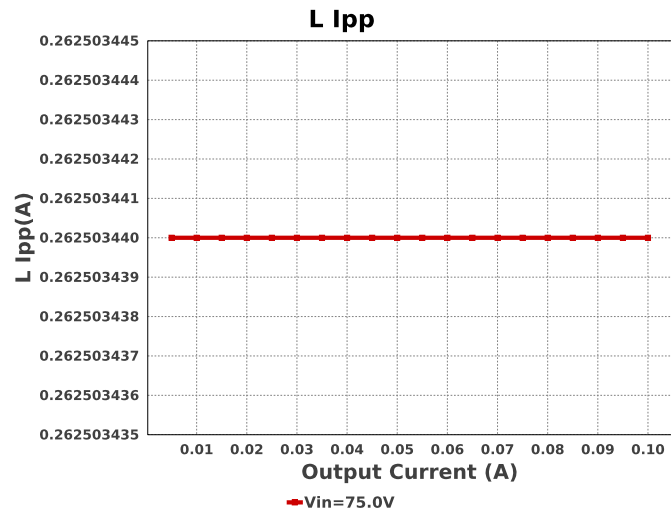
Component Selection Information

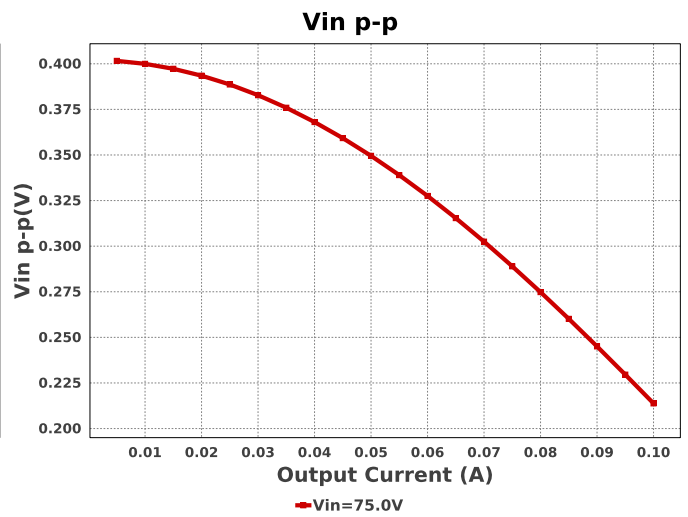
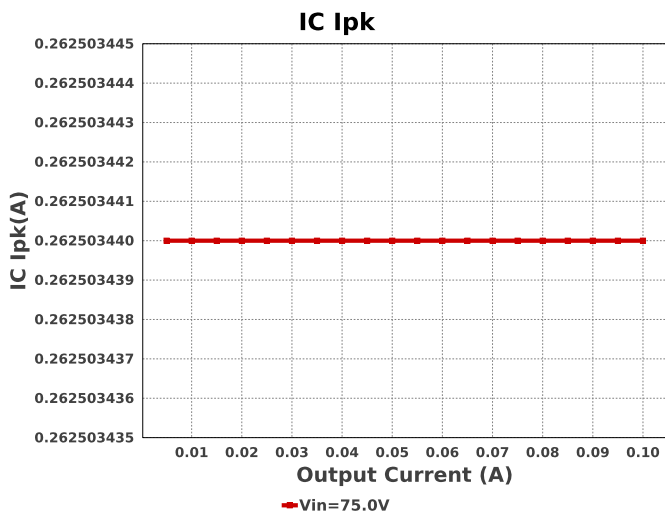
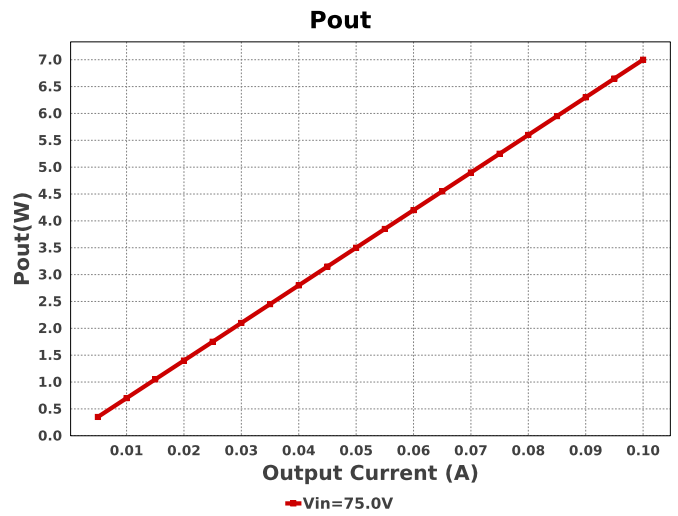
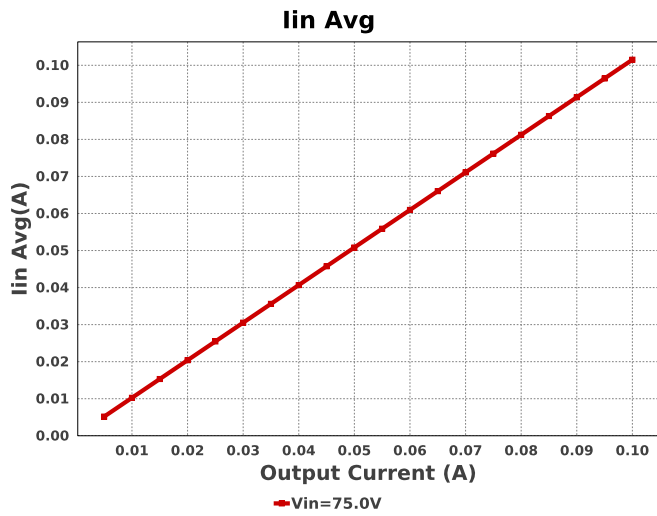
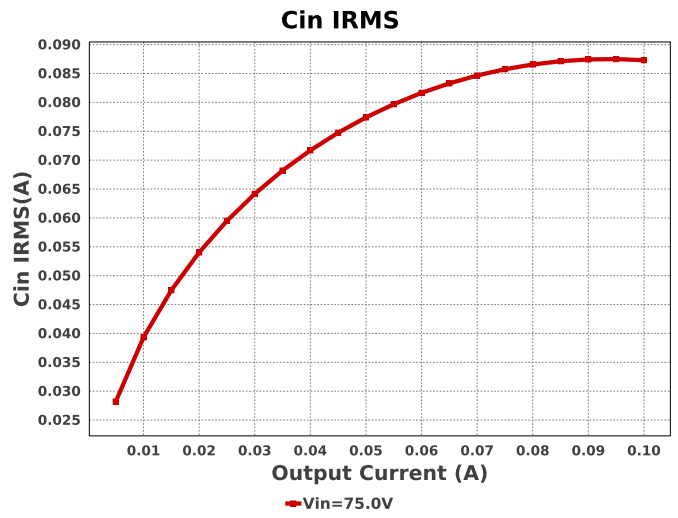
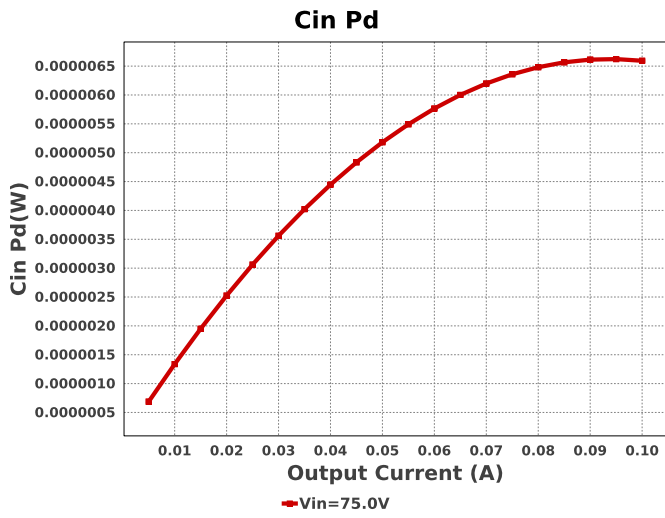
WARNING: Device is functioning in Dropout. This device support spread spectrum feature which is not modeled on WEBENCH. This device can work in steady state at Vin = 4.2V. However, needs a minimum of 4.5V during start up. See datasheet for details.

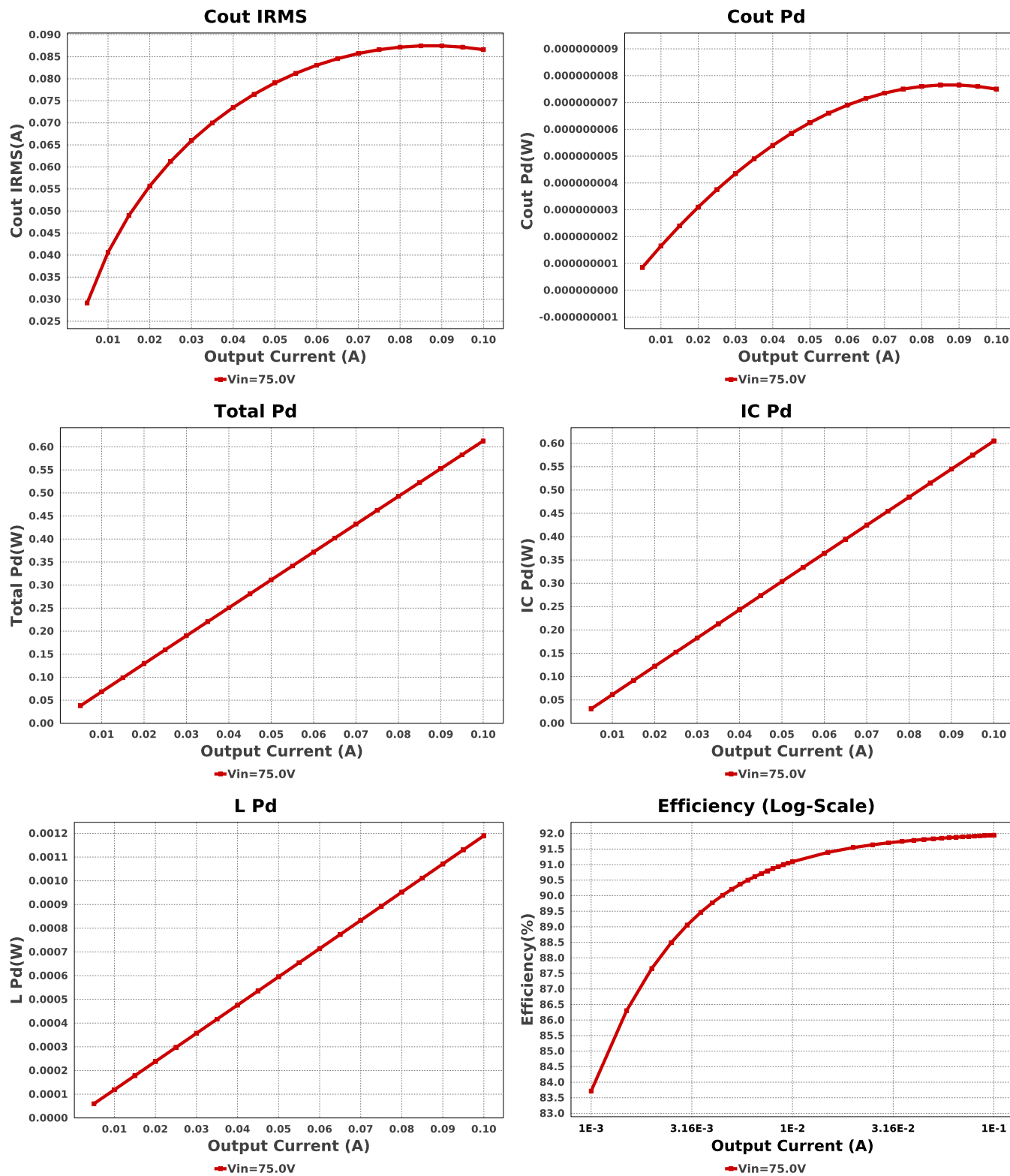
Electrical BOM

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Cboot	MuRata	GRM155R71C104KA88D Series= X7R	Cap= 100.0 nF ESR= 1.0 mOhm VDC= 16.0 V IRMS= 0.0 A	1	\$0.01	 0402 3 mm ²
Cin	TDK	C3225X7R2A225K230AB Series= X7R	Cap= 2.2 uF ESR= 1.73 mOhm VDC= 100.0 V IRMS= 5.5932 A	2	\$0.21	 1210_250 15 mm ²
Cinx	TDK	C2012X7R2A104K125AA Series= X7R	Cap= 100.0 nF ESR= 20.726 mOhm VDC= 100.0 V IRMS= 1.456 A	1	\$0.03	 0805 7 mm ²
Cout	CUSTOM	CUSTOM Series= ?	Cap= 20.0 uF ESR= 1.0 uOhm VDC= 140.0 V IRMS= 123.72 mA	1	NA	CUSTOM 0 mm ²
L1	Coilcraft	MSS1210-683MEB	L= 68.0 uH 68.0 mOhm	1	\$0.81	 MSS1210 204 mm ²
Rfbb	Vishay-Dale	CRCW040210K0FKED Series= CRCW..e3	Res= 10.0 kOhm Power= 63.0 mW Tolerance= 1.0%	1	\$0.01	 0402 3 mm ²
Rfbt	Vishay-Dale	CRCW0805698KFKEA Series= CRCW..e3	Res= 698.0 kOhm Power= 125.0 mW Tolerance= 1.0%	1	\$0.01	 0805 7 mm ²
Rpgood	Vishay-Dale	CRCW0603100KFKEA Series= CRCW..e3	Res= 100.0 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm ²

Name	Manufacturer	Part Number	Properties	Qty	Price	Footprint
Rt	Vishay-Dale	CRCW060364K9FKEA Series= CRCW..e3	Res= 64.9 kOhm Power= 100.0 mW Tolerance= 1.0%	1	\$0.01	 0603 5 mm²
U1	Texas Instruments	LMR38010SDDAR	Switcher	1	\$1.11	 DDA0008E_N 55 mm²







Operating Values

#	Name	Value	Category	Description
1.	Cin IRMS	87.303 mA	Capacitor	Input capacitor RMS ripple current
2.	Cin Pd	6.593 μ W	Capacitor	Input capacitor power dissipation
3.	Cout IRMS	86.604 mA	Capacitor	Output capacitor RMS ripple current
4.	Cout Pd	7.5 nW	Capacitor	Output capacitor power dissipation
5.	IC Ipk	262.503 mA	IC	Peak switch current in IC
6.	IC Pd	604.88 mW	IC	IC power dissipation
7.	IC Tj	47.542 degC	IC	IC junction temperature
8.	IC Tolerance	5.0 mV	IC	IC Feedback Tolerance
9.	ICThetaJA Effective	29.0 degC/W	IC	Effective IC Junction-to-Ambient Thermal Resistance
10.	Iin Avg	101.51 mA	IC	Average input current

#	Name	Value	Category	Description
11.	Ipp percentage	262.503 %	Inductor	Inductor ripple current percentage (with respect to average inductor current)
12.	L Ipp	262.5 mA	Inductor	Peak-to-peak inductor ripple current
13.	L Pd	1.19 mW	Inductor	Inductor power dissipation
14.	Cin Pd	6.593 μ W	Power	Input capacitor power dissipation
15.	Cout Pd	7.5 nW	Power	Output capacitor power dissipation
16.	IC Pd	604.88 mW	Power	IC power dissipation
17.	L Pd	1.19 mW	Power	Inductor power dissipation
18.	Total Pd	613.019 mW	Power	Total Power Dissipation
19.	BOM Count	11	System	Total Design BOM count
20.	Duty Cycle	71.15 %	System Information	Duty cycle
21.	Efficiency	91.948 %	System Information	Steady state efficiency
22.	FootPrint	358.0 mm ²	System Information	Total Foot Print Area of BOM components
23.	Frequency	197.67 kHz	System Information	Switching frequency
24.	Inductor ripple current requirement used for Inductor selection	40.0 %	System Information	Custom Inductor ripple current (% of average inductor current) requirement used for Inductor selection
25.	Iout	100.0 mA	System Information	Iout operating point
26.	Iout transient step used for Cout calculations	50.0 mA	System Information	Custom Transient current step requirement that was used for Cout selection (A).
27.	Mode	PFM	System Information	Conduction Mode
28.	Overshoot Value	60.714 μ V	System Information	Theoretical Vout Overshoot Value
29.	Pout	7.0 W	System Information	Total output power
30.	Total BOM	NA	System Information	Total BOM Cost
31.	Undershoot Value	1.693 mV	System Information	Theoretical Vout Undershoot Value
32.	Vin	75.0 V	System Information	Vin operating point
33.	Vin p-p	213.796 mV	System Information	Peak-to-peak input voltage
34.	Vout	70.0 V	System Information	Operational Output Voltage
35.	Vout Actual	70.8 V	System Information	Vout Actual calculated based on selected voltage divider resistors
36.	Vout Ripple requirement used for Cout calculations	1.0 %	System Information	Custom maximum output ripple requirement that was used for Cout selection(% of Vout).
37.	Vout Tolerance	2.502 %	System Information	Vout Tolerance based on IC Tolerance (no load) and voltage divider resistors if applicable
38.	Vout p-p	9.694 mV	System Information	Peak-to-peak output ripple voltage
39.	Vout transient requirement used for Cout calculations	3.0 %	System Information	Custom Transient voltage change requirement that was used for Cout selection (% of Vout).

Design Inputs

Name	Value	Description
Iout	100.0 m	Maximum Output Current
VinMax	75.0	Maximum input voltage
VinMin	75.0	Minimum input voltage
Vout	70.0	Output Voltage
base_pn	LMR38010S	Base Product Number
source	DC	Input Source Type
Ta	30.0	Ambient temperature

WEBENCH® Assembly

Component Testing

Some published data on components in datasheets such as Capacitor ESR and Inductor DC resistance is based on conservative values that will guarantee that the components always exceed the specification. For design purposes it is usually better to work with typical values. Since this data is not always available it is a good practice to measure the Capacitance and ESR values of C_{in} and C_{out} , and the inductance and DC resistance of L_1 before assembly of the board. Any large discrepancies in values should be electrically simulated in WEBENCH to check for instabilities and thermally simulated in WebTHERM to make sure critical temperatures are not exceeded.

Soldering Component to Board

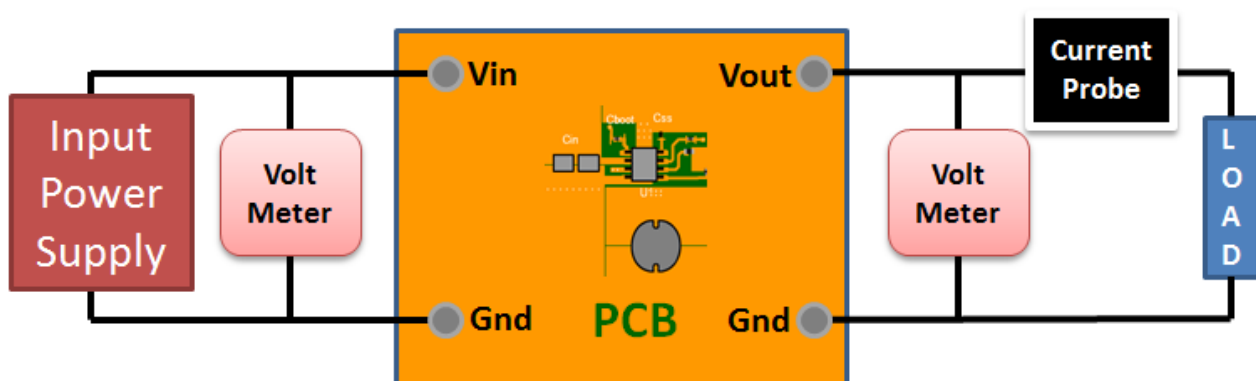
If board assembly is done in house it is best to tack down one terminal of a component on the board then solder the other terminal. For surface mount parts with large tabs, such as the DPAK, the tab on the back of the package should be pre-tinned with solder, then tacked into place by one of the pins. To solder the tab down to the board place the iron down on the board while resting against the tab, heating both surfaces simultaneously. Apply light pressure to the top of the plastic case until the solder flows around the part and the part is flush with the PCB. If the solder is not flowing around the board you may need a higher wattage iron (generally 25W to 30W is enough).

Initial Startup of Circuit

It is best to initially power up the board by setting the input supply voltage to the lowest operating input voltage 75.0V and set the input supply's current limit to zero. With the input supply off connect up the input supply to V_{in} and GND. Connect a digital volt meter and a load if needed to set the minimum load of the design from V_{out} and GND. Turn on the input supply and slowly turn up the current limit on the input supply. If the voltage starts to rise on the input supply continue increasing the input supply current limit while watching the output voltage. If the current increases on the input supply, but the voltage remains near zero, then there may be a short or a component misplaced on the board. Power down the board and visually inspect for solder bridges and recheck the diode and capacitor polarities. Once the power supply circuit is operational then more extensive testing may include full load testing, transient load and line tests to compare with simulation results.

Load Testing

The setup is the same as the initial startup, except that an additional digital voltmeter is connected between V_{in} and GND, a load is connected between V_{out} and GND and a current meter is connected in series between V_{out} and the load. The load must be able to handle at least rated output power + 50% (7.5 watts for this design). Ideally the load is supplied in the form of a variable load test unit. It can also be done in the form of suitably large power resistors. When using an oscilloscope to measure waveforms on the prototype board, the ground leads of the oscilloscope probes should be as short as possible and the area of the loop formed by the ground lead should be kept to a minimum. This will help reduce ground lead inductance and eliminate EMI noise that is not actually present in the circuit.



Design Assistance

1. Master key : C27FA4700EC3514E[v1]
2. **LMR38010S** Product Folder : <http://www.ti.com/product/LMR38010> : contains the data sheet and other resources.

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